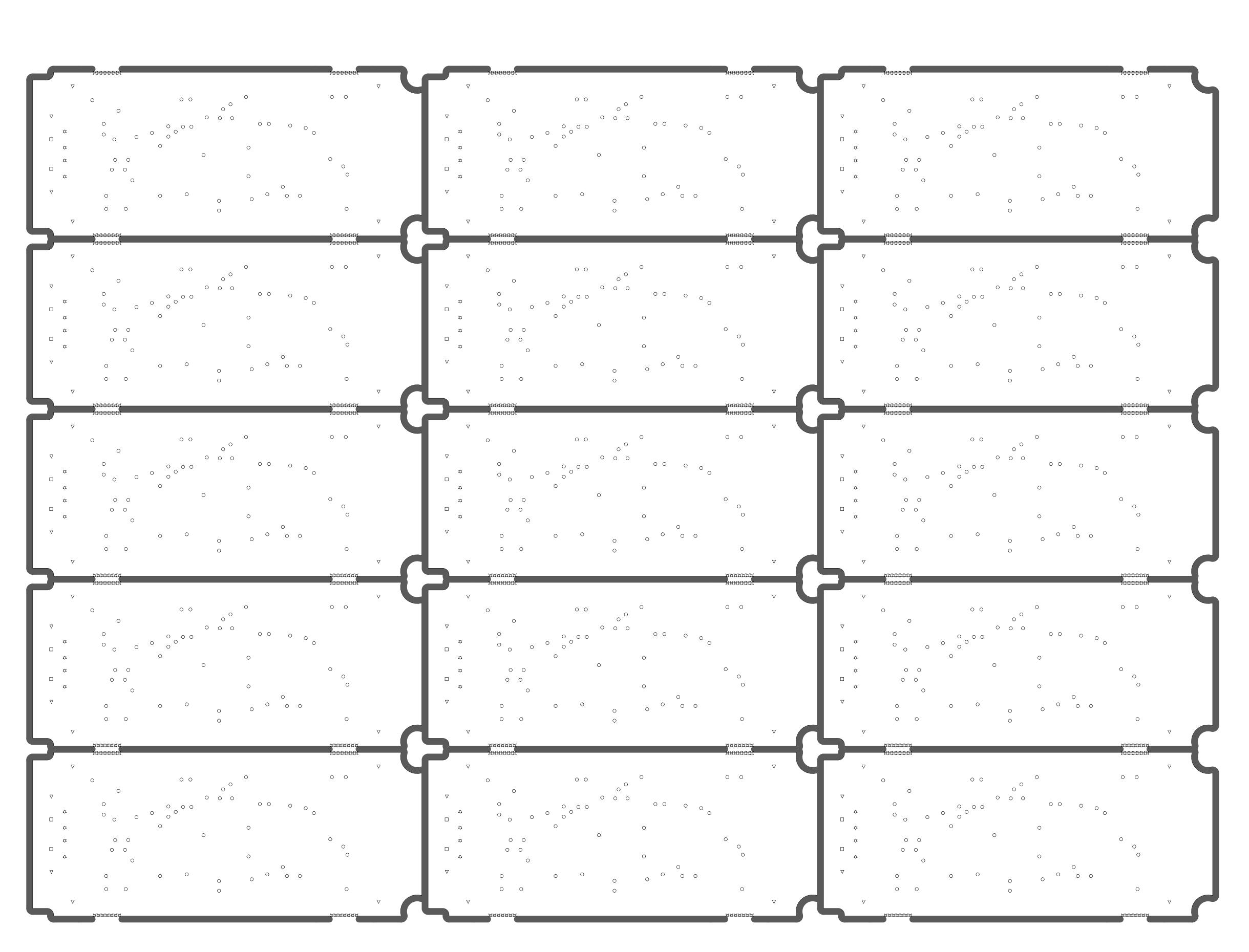


Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	O. 010mm	3.5	
3	Top Layer	Copper	0.036mm		
4	Dielectric 1	FR-4	1.600mm	4.8	
5	Bottom Layer	Copper	0.036mm		
6	Bottom Solder	Solder Resist	O. 010mm	3.5	
7	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
×	420	19,69mil (0,500mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
0	780	20,00mil (0,508mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
❖	60	27,56mil (0,700mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
	30	40,00mil (1,016mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
∇	90	86,61mil (2,200mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	1380 Total						



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